



Material Content Data Sheet



Sales Product Name		BTS141		Issued		20. July 2018		
MA#		MA001017972						
Package		PG-TO220-3-1		Weight*		2023.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.593	0.77	0.77	7707	7707
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		121	
	non noble metal	iron	7439-89-6	0.816	0.04		403	
	non noble metal	copper	7440-50-8	815.335	40.30	40.35	402967	403491
	non noble metal	aluminium	7429-90-5	1.315	0.06	0.06	650	650
wire	non noble metal	aluminium	7429-90-5	1.315	0.06	0.06	650	650
encapsulation	organic material	carbon black	1333-86-4	6.292	0.31		3110	
	inorganic material	antimonytrioxide	1309-64-4	13.157	0.65		6503	
	plastics	brominated resin	-	14.873	0.74		7351	
	plastics	epoxy resin	-	108.686	5.37		53717	
	inorganic material	silicondioxide	60676-86-0	429.025	21.20	28.27	212040	282721
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10607	10607
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	121	122
glue	plastics	Polyimide	26023-21-2	0.586	0.03	0.03	290	290
solder	non noble metal	tin	7440-31-5	0.109	0.01		54	
	noble metal	silver	7440-22-4	0.136	0.01		67	
	non noble metal	lead	7439-92-1	5.213	0.26	0.28	2576	2697
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		88	
	non noble metal	iron	7439-89-6	0.590	0.03		292	
	non noble metal	copper	7440-50-8	589.466	29.13	29.17	291335	291715
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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